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## Product Change Notification - JAON-29UDMC755 [\(Printer Friendly\)](#)

**Date:** 29 Jan 2015

**Notification subject:** CCB 1444.03 Final Notice: Qualification of palladium coated copper (PdCu) bond wire for selected products of 150K and 160K wafer technologies in 8L SOIC package at MMT assembly site.

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

See attachments of affected catalog part numbers (CPN) labeled as...  
PCN\_JAON-29UDMC755\_Affected\_CPN.xls  
PCN\_JAON-29UDMC755\_Affected\_CPN.pdf

**Description of Change:**

Qualification of palladium coated copper (PdCu) bond wire for selected products of 150K and 160K wafer technologies in 8L SOIC package at MMT assembly site.

**Pre Change:**

Gold (Au) bond wire.

**Post Change:**

Palladium coated Copper (PdCu) bond wire or Gold (Au) bond wire.

**Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability and qualify PdCu bond wire at MMT assembly site.

**Change Implementation Status:**

Complete

**Estimated First Ship Date:**

February 16, 2015 (date code: 1508)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**August 18, 2014:** Issued initial notification.

**January 29, 2015:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from November 10, 2014 to February 16, 2015.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-29UDMC755\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-29UDMC755\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-29UDMC755\\_Affected\\_CPN.xls](#)

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